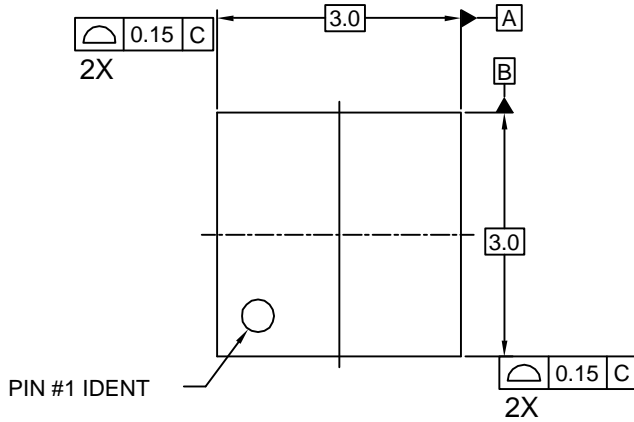


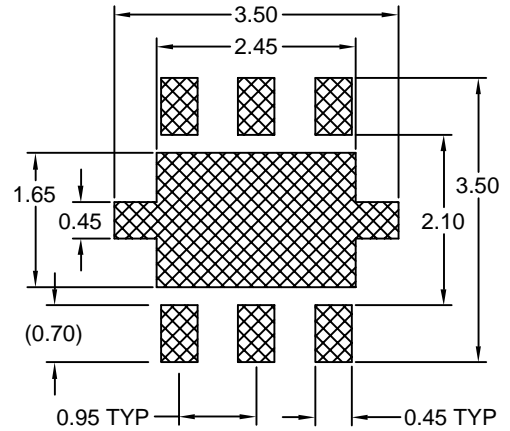
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REVISIONS

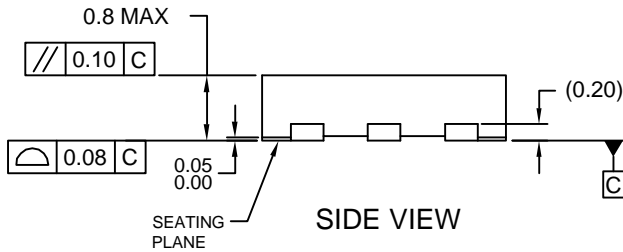
LTR	DESCRIPTION	EDCN	DATE	BY/APPD
A	RELEASE TO DOCUMENT CONTROL	ECN-MKT-MLP06F	22-3-2004	FEITAN



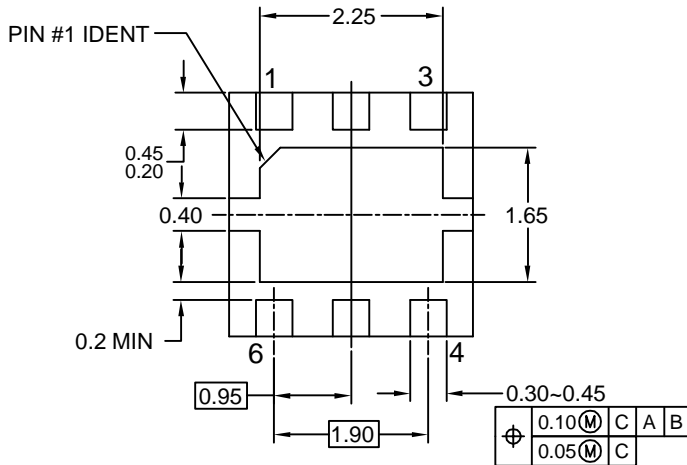
TOP VIEW



RECOMMENDED LAND PATTERN



SIDE VIEW



BOTTOM VIEW

NOTES:

- A. CONFORMS TO JEDEC REGISTRATION MO-229, VARIATION WEEA, DATED 11/2001 EXCEPT FOR DAP EXTENSION TABS
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994

MLP06FrevA

APPROVALS	DATE	FAIRCHILD Bayan Lepas, FIZ, SEMICONDUCTOR™ 11900, Penang, Malaysia.			
DRAWN FEITAN	18-3-2004	6LD,MLP,DUAL,JEDEC MO-229, 3MM SQUARE, EXTENDED DAP			
DFTG. CHK.					
ENGR. CHK.					
		SCALE N/A	SIZE N/A	DRAWING NUMBER MKT-MLP06F	REV A
		DO NOT SCALE DRAWING		SHEET 1 of 1	